

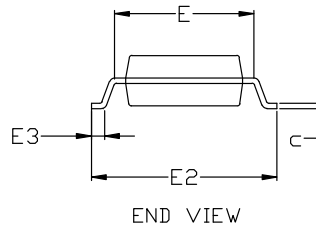
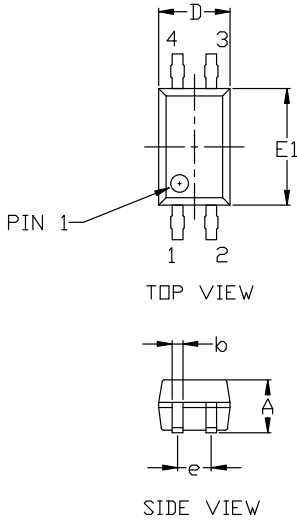
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



MFP4 2.7x4.4, 1.27P
CASE 100EB
ISSUE O

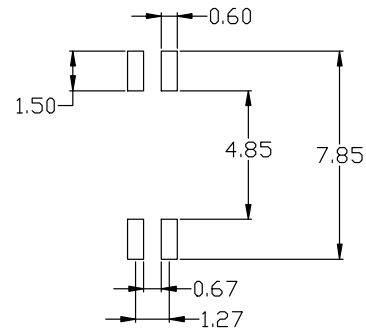
DATE 08 SEP 2022



NOTES:

- A) NO STANDARD APPLIES TO THIS PACKAGE.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSION

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	2.00
b	0.30	0.40	0.50
c	0.20 REF		
D	2.50	2.70	2.90
E	5.2 TYP		
E1	4.20	4.40	4.60
E2	6.70	7.00	7.30
E3	0.50	---	---
e	1.27 TYP		



RECOMMENDED
MOUNTING
FOOTPRINT*

- * For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	MFP4 2.7x4.4, 1.27P	PAGE 1 OF 1

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